This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

**PCN Title:** Package Material Changes for SOT23, MiniSO, MQFP, PDIP, PLCC, SOIC (narrow and wide body), SSOP, TSSOP and TSSOP exposed pad

**Publication Date:** 19-Aug-2009

**Samples Available Date:**

**Effectivity Date:** 19-Aug-2009 (the earliest date that a customer could expect to receive changed material)

### Description Of Change

In response to Sumitomo’s announcement that the supply of 6300H, 6650RL, 6710S, 6730B, and 7050B is being discontinued, ADI is changing mold compound materials, and in some cases die attach materials, for SOT23, MiniSO, MQFP, PDIP, PLCC, SOIC (narrow and wide body), SSOP, TSSOP (4.4 mm body), and TSSOP exposed pad packages.

This activity is being done in conjunction with the polyimide implementation. Some products are converting to previously qualified materials, such as Ablestik 8290, Sumitomo 6600, Sumitomo 7351, and Nitto MP8000. Other products are converting to newly qualified materials, such as Sumitomo 6730B-L, Sumitomo G600, and Sumitomo G700.

Refer to the attached Parts List which includes the ADI affected product models, their current (existing) materials, and their new materials. For those products listed with more than one new die attach and/or new molding compound material, a final decision on the material set has yet to be defined and will be clarified on a future revision of this PCN. Within the Parts List table, the blue font indicates any change from the prior PCN revision.

The Effectivity Date included in the Parts List defines the earliest possible date that our customer could expect to receive the changed material. The Actual Effectivity Date Code in the Parts List indicates the earliest actual date code product models could be assembled with the changed materials. For some product models, finished goods inventory assembled with the existing materials will continue to ship for a period of time to deplete current inventories.

### Reason For Change

Mold compound changes are driven by Sumitomo's announcement that the supply of 6300H, 6650RL, 6710S, 6730B, and 7050B is being discontinued. Die attach material changes are being done to align with our materials standardization strategy. Polyimide implementation has been advised through prior PCN announcements.

### Impact of the change (positive or negative) on fit, form, function & reliability

There are no changes to the wire diameter (except where noted in the comments column of the Parts List), wire type, package quality or reliability.

### Summary of Supporting Information

Qualifications are being performed per Analog Devices specification ADI0012, Procedure for Qualification of New or Revised Processes or Products. Typical package qualification tests are listed below. Supporting qualification data is included as an attachment to this PCN. New qualification data will be added in subsequent revisions to this PCN.

- **Highly Accelerated Stress**, JEDEC JESD22-A110 (Preconditioned Per JEDEC/IPC J-STD-020)
- **Temperature, Humidity Bias**, JEDEC JESD22-A101 (Preconditioned Per JEDEC/IPC J-STD-020)
- **Autoclave**, JEDEC JESD22-A102 (Preconditioned Per JEDEC/IPC J-STD-020)
- **Temperature Cycle**, JEDEC JESD22-A104 (Preconditioned Per JEDEC/IPC J-STD-020)
- **High Temperature Storage**, JEDEC JESD22-A103
- **Typical Sample Size**: 45pcs/Lot

Refer to attachment for summary of available qualification data.

### Supporting Documents

- **Attachment 1**: ADI_PCN_07_0024_Rev_E_Qual Data.pdf
- **Attachment 2**: ADI_PCN_07_0024_Rev_E_Parts List.pdf

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**For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative**

**Americas:** PCN_Americas@analog.com

**Europe:** PCN_Europe@analog.com

**Japan:** PCN_Japan@analog.com

**Rest of Asia:** PCN_ROA@analog.com
<table>
<thead>
<tr>
<th>Rev</th>
<th>Publish Date</th>
<th>Rev Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Rev. -</td>
<td>07-Dec-2007</td>
<td>Initial Release</td>
</tr>
<tr>
<td>Rev. B</td>
<td>23-Jul-2008</td>
<td>Rev B: Updated July 21 2008 to include effectivity dates for some products shown on Parts List</td>
</tr>
<tr>
<td>Rev. C</td>
<td>07-Nov-2008</td>
<td>Rev C: Updated November 7 2008 to modify Text Parts List Qualification Data and Effectivity Dates</td>
</tr>
<tr>
<td>Rev. D</td>
<td>31-Mar-2009</td>
<td>Rev D includes an update to actual effectivity date codes for product conversions and adds a few new finished goods models to Parts List. No change to text or qualification data.</td>
</tr>
<tr>
<td>Rev. E</td>
<td>19-Aug-2009</td>
<td>Update Parts List to add new conversion date codes and comments. Update &quot;Anticipated Impact of the Change&quot; to include a comment that any wire diameter changes will be documented in the Parts List.</td>
</tr>
</tbody>
</table>